

UTILITY PATENT APPLICATION

HONORABLE COMMISSIONER OF
PATENTS AND TRADEMARKS
Washington D.C. 20231

Docket No.: 3008-28
Client Ref.: PHNF-01094

J1046 U.S. PTO
09/892630
06/28/01

06/28/01

J1051 U.S. PTO

Sir:

Transmitted herewith for filing is the patent application of:

INVENTOR(S): Seigi Aoyama, Takaaki Ichikawa, Hiromitsu Kuroda, Takashi Nemoto, Atsushi Ohtake and Hiroyoshi Hiruta
FOR: LEAD FREE SOLDER, AND CONNECTION LEAD AND ELECTRICAL COMPONENT USING SAID LEAD FREE SOLDER

Enclosed are:

- ☒ 24 pages of specification, claims, abstract
- ☒ Declaration & Power of Attorney.
- ☒ Priority Claimed
- ☒ 4 sheets of drawing.
- ☒ An assignment of the invention to Hitachi Cable Ltd. and the assignment recordation fee.
- ☒ Certified copy of _____ JP Application No. 2001-61650
- ☐ An associate power of attorney.
- ☐ Preliminary Amendment
- ☒ Information Disclosure Statement, Form PTO-1449 and reference.

The filing fee has been calculated as shown below:

(1) FOR	(2) NO. FILED	(3) NO. EXTRA	(4) RATE	(5) AMOUNT
TOTAL CLAIMS	13	-20	0	x \$18.00 = \$.00
INDEPENDENT CLAIMS	3	-3	0	x \$80.00 = .00
MULTIPLE DEPENDENT CLAIM(S) (If applicable)				+ \$ ____ .00 = 00.00
BASIC FEE				\$710.00
Total of above calculations				= \$710.00
Subtract ½ if Small Entity				= \$ ____ .00
[X] Assignment & Recording Fee				\$40.00
TOTAL FEE				\$750.00

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